

## General Description

FSMOS<sup>®</sup> MOSFET is based on Oriental Semiconductor's unique device design to achieve low  $R_{DS(ON)}$ , low gate charge, fast switching and excellent avalanche characteristics. The high  $V_{th}$  series is specially designed to use in power supply systems with driving voltage of more than 10V.

## Features

- Low  $R_{DS(ON)}$  & FOM
- Extremely low switching loss
- Excellent reliability and uniformity
- Fast switching and soft recovery



## Applications

- Switched mode power supply
- Motor driver
- Battery protection
- DC-DC convertor
- Inverters
- UPS

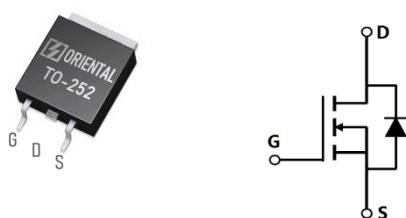
## Key Performance Parameters

| Parameter                      | Value | Unit |
|--------------------------------|-------|------|
| $V_{DS, min} @ T_{j(max)}$     | 40    | V    |
| $I_D, pulse$                   | 390   | A    |
| $R_{DS(ON), max} @ V_{GS}=10V$ | 2.5   | mΩ   |
| $Q_g$                          | 107   | nC   |

## Marking Information

| Product Name | Package | Marking    |
|--------------|---------|------------|
| SFS04R02DNF  | TO252   | SFS04R02DN |

## Package & Pin information



**Absolute Maximum Ratings** at  $T_j=25^\circ\text{C}$  unless otherwise noted

| Parameter   | Symbol               | Value      | Unit             |
|---|----------------------|------------|------------------|
| Drain-source voltage  | $V_{DS}$             | 40         | V                |
| Gate-source voltage   | $V_{GS}$             | $\pm 20$   | V                |
| Continuous drain current <sup>1)</sup> , $T_C=25^\circ\text{C}$         | $I_D$                | 130        | A                |
| Pulsed drain current <sup>2)</sup> , $T_C=25^\circ\text{C}$             | $I_{D,\text{pulse}}$ | 390        | A                |
| Continuous diode forward current <sup>1)</sup> , $T_C=25^\circ\text{C}$ | $I_S$                | 130        | A                |
| Diode pulsed current <sup>2)</sup> , $T_C=25^\circ\text{C}$             | $I_{S,\text{pulse}}$ | 390        | A                |
| Power dissipation <sup>3)</sup> , $T_C=25^\circ\text{C}$                | $P_D$                | 140        | W                |
| Single pulsed avalanche energy <sup>5)</sup>                            | $E_{AS}$             | 240        | mJ               |
| Operation and storage temperature                                       | $T_{stg}, T_j$       | -55 to 175 | $^\circ\text{C}$ |

**Thermal Characteristics**

| Parameter  | Symbol          | Value | Unit                      |
|--|-----------------|-------|---------------------------|
| Thermal resistance, junction-case                  | $R_{\theta JC}$ | 1.07  | $^\circ\text{C}/\text{W}$ |
| Thermal resistance, junction-ambient <sup>4)</sup> | $R_{\theta JA}$ | 62    | $^\circ\text{C}/\text{W}$ |

**Electrical Characteristics** at  $T_j=25^\circ\text{C}$  unless otherwise specified

| Parameter                        | Symbol              | Min. | Typ. | Max. | Unit             | Test condition                            |
|----------------------------------|---------------------|------|------|------|------------------|---|
| Drain-source breakdown voltage   | $BV_{DSS}$          | 40   |      |      | V                | $V_{GS}=0 \text{ V}, I_D=250 \mu\text{A}$ |
| Gate threshold voltage           | $V_{GS(\text{th})}$ | 2.0  |      | 4.0  | V                | $V_{DS}=V_{GS}, I_D=250 \mu\text{A}$      |
| Drain-source on-state resistance | $R_{DS(\text{ON})}$ |      | 2.0  | 2.5  | $\text{m}\Omega$ | $V_{GS}=10 \text{ V}, I_D=55 \text{ A}$   |
| Gate-source leakage current      | $I_{GSS}$           |      |      | 100  | nA               | $V_{GS}=20 \text{ V}$                     |
|                                  |                     |      |      | -100 |                  | $V_{GS}=-20 \text{ V}$                    |
| Drain-source leakage current     | $I_{DSS}$           |      |      | 1    | $\mu\text{A}$    | $V_{DS}=40 \text{ V}, V_{GS}=0 \text{ V}$ |
| Gate resistance                  | $R_G$               |      | 2    |      | $\Omega$         | $f=1 \text{ MHz}, \text{Open drain}$      |

### Dynamic Characteristics

| Parameter                    | Symbol              | Min. | Typ. | Max. | Unit | Test condition   |
|------------------------------|---------------------|------|------|------|------|--|
| Input capacitance            | C <sub>iss</sub>    |      | 9096 |      | pF   | V <sub>GS</sub> =0 V,<br>V <sub>DS</sub> =25 V,<br>f=100 kHz                                     |
| Output capacitance           | C <sub>oss</sub>    |      | 1493 |      | pF   |  |
| Reverse transfer capacitance | C <sub>rss</sub>    |      | 69.2 |      | pF   |  |
| Turn-on delay time           | t <sub>d(on)</sub>  |      | 30.7 |      | ns   | V <sub>GS</sub> =10 V,<br>V <sub>DS</sub> =20 V,<br>R <sub>G</sub> =2 Ω,<br>I <sub>D</sub> =20 A |
| Rise time                    | t <sub>r</sub>      |      | 38.1 |      | ns   |  |
| Turn-off delay time          | t <sub>d(off)</sub> |      | 72.3 |      | ns   |  |
| Fall time                    | t <sub>f</sub>      |      | 21.9 |      | ns   |  |

### Gate Charge Characteristics

| Parameter            | Symbol               | Min. | Typ. | Max. | Unit | Test condition   |
|----------------------|----------------------|------|------|------|------|--|
| Total gate charge    | Q <sub>g</sub>       |      | 107  |      | nC   | V <sub>GS</sub> =10 V,<br>V <sub>DS</sub> =20 V,<br>I <sub>D</sub> =20 A |
| Gate-source charge   | Q <sub>gs</sub>      |      | 34   |      | nC   |  |
| Gate-drain charge    | Q <sub>gd</sub>      |      | 10   |      | nC   |  |
| Gate plateau voltage | V <sub>plateau</sub> |      | 4.3  |      | V    |  |

### Body Diode Characteristics

| Parameter                     | Symbol           | Min. | Typ. | Max. | Unit | Test condition   |
|-------------------------------|------------------|------|------|------|------|--|
| Diode forward voltage         | V <sub>SD</sub>  |      |      | 1.3  | V    | I <sub>s</sub> =20 A,<br>V <sub>GS</sub> =0 V                    |
| Reverse recovery time         | t <sub>rr</sub>  |      | 47   |      | ns   | V <sub>R</sub> =20 V,<br>I <sub>s</sub> =20 A,<br>di/dt=100 A/μs |
| Reverse recovery charge       | Q <sub>rr</sub>  |      | 35.4 |      | nC   |  |
| Peak reverse recovery current | I <sub>rrm</sub> |      | 1.3  |      | A    |  |

### Note

- 1) Calculated continuous current based on maximum allowable junction temperature.
- 2) Repetitive rating; pulse width limited by max. junction temperature.
- 3) Pd is based on max. junction temperature, using junction-case thermal resistance.
- 4) The value of R<sub>θJA</sub> is measured with the device mounted on 1 in 2 FR-4 board with 2oz. Copper, in a still air environment with T<sub>a</sub>=25 °C.
- 5) V<sub>DD</sub>=30 V, V<sub>GS</sub>=10 V, L=0.3 mH, starting T<sub>j</sub>=25 °C.

## Electrical Characteristics Diagrams

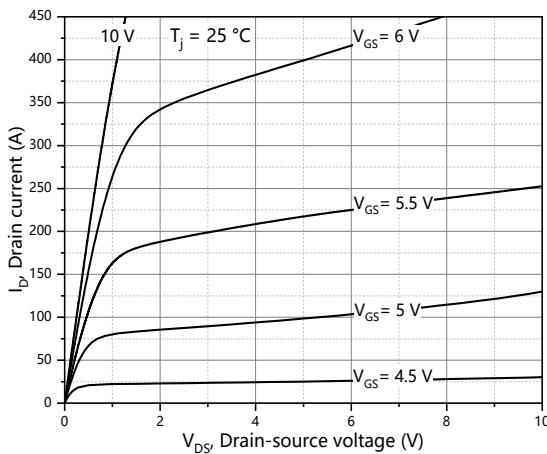


Figure 1. Typ. output characteristics

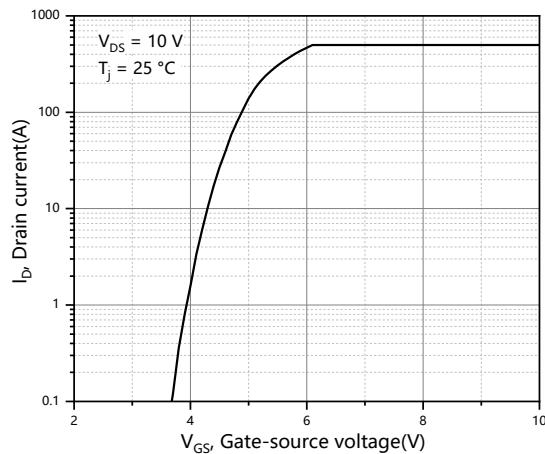


Figure 2. Typ. transfer characteristics

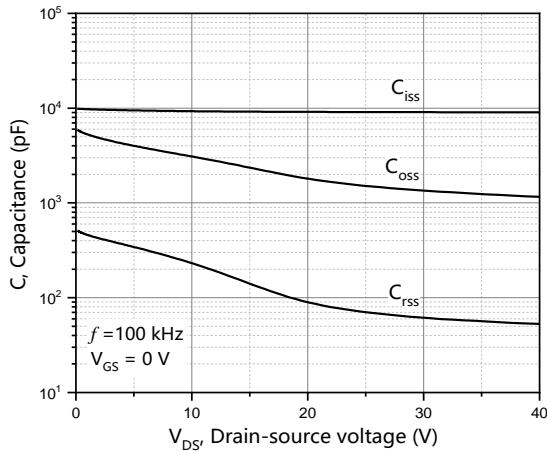


Figure 3. Typ. capacitances

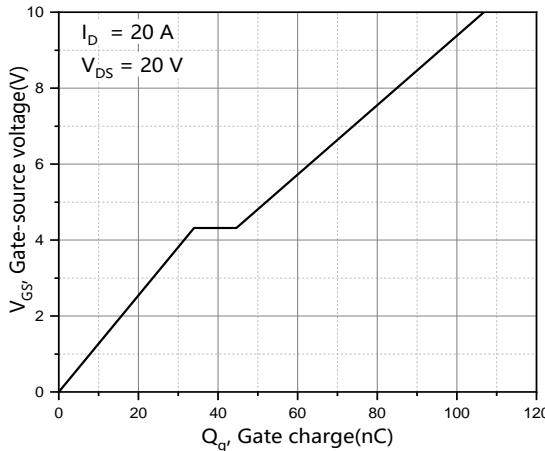


Figure 4. Typ. gate charge

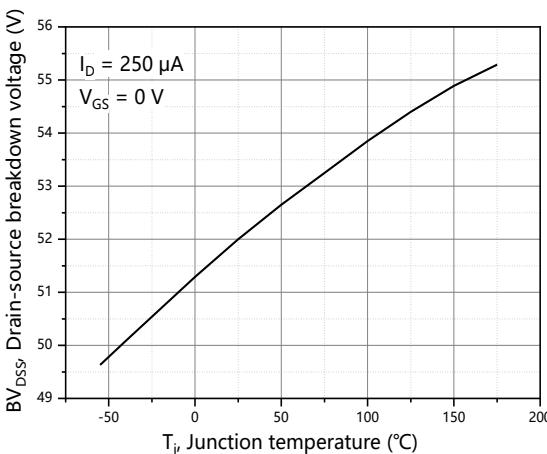


Figure 5. Drain-source breakdown voltage

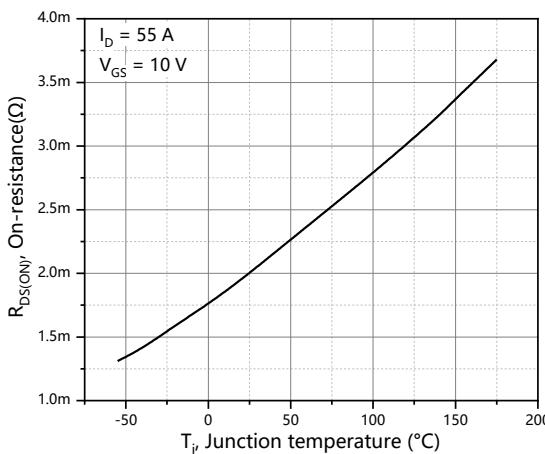
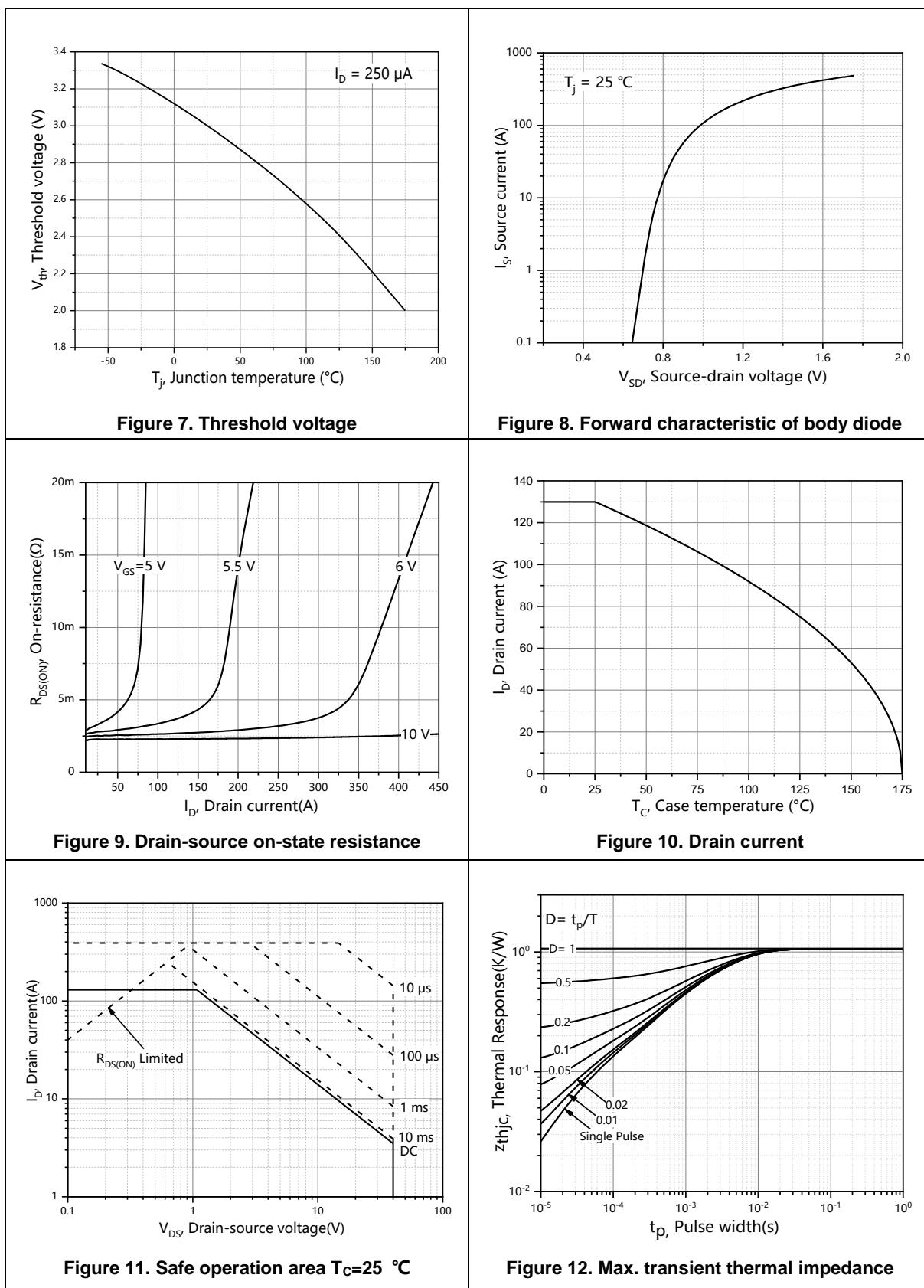
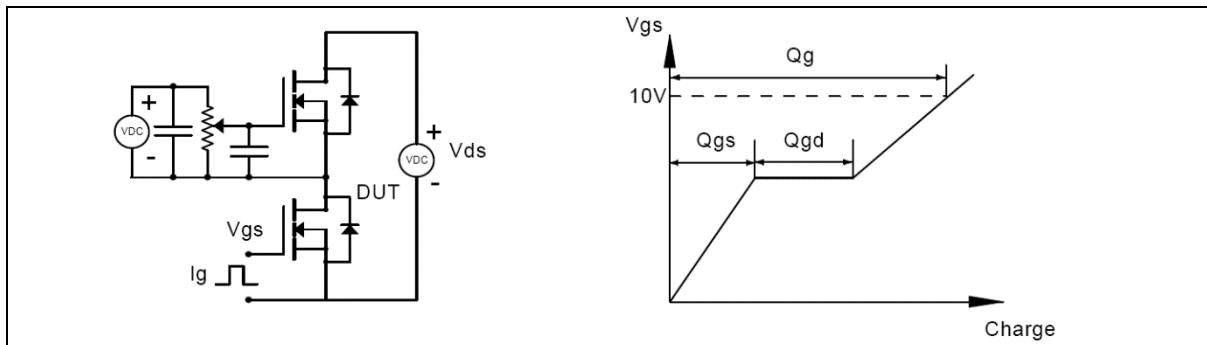


Figure 6. Drain-source on-state resistance



### Test circuits and waveforms



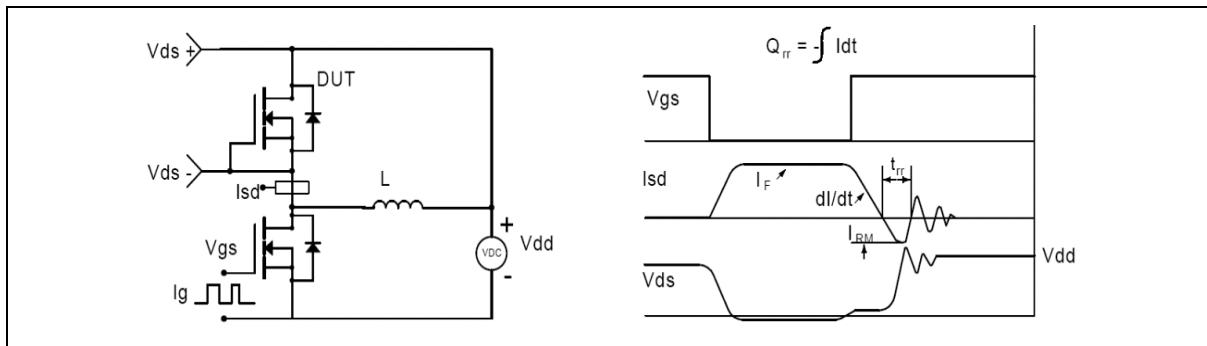
**Figure 1. Gate charge test circuit & waveform**



**Figure 2. Switching time test circuit & waveforms**

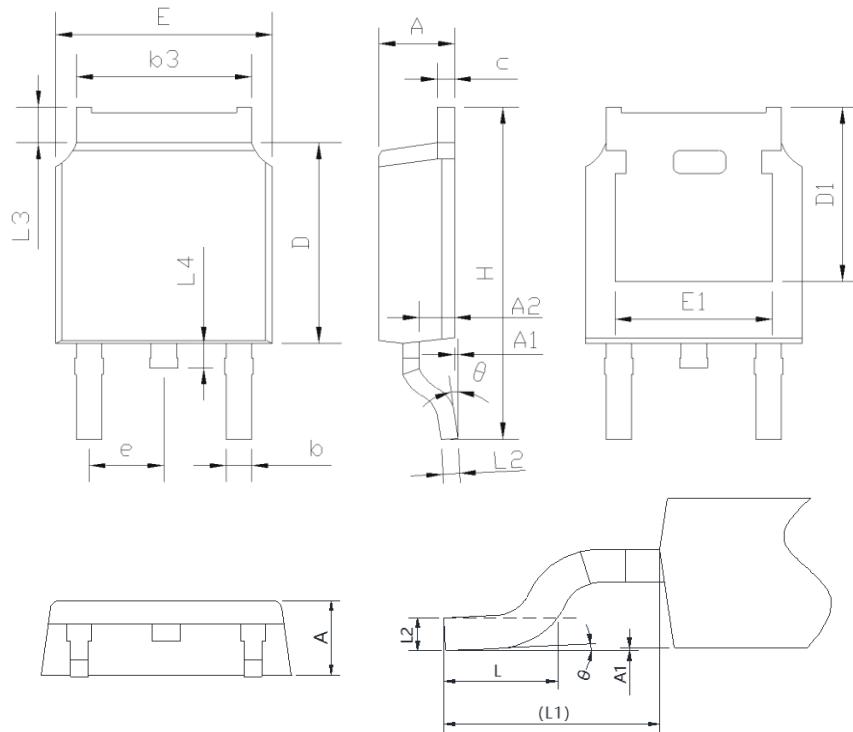


**Figure 3. Unclamped inductive switching (UIS) test circuit & waveforms**



**Figure 4. Diode reverse recovery test circuit & waveforms**

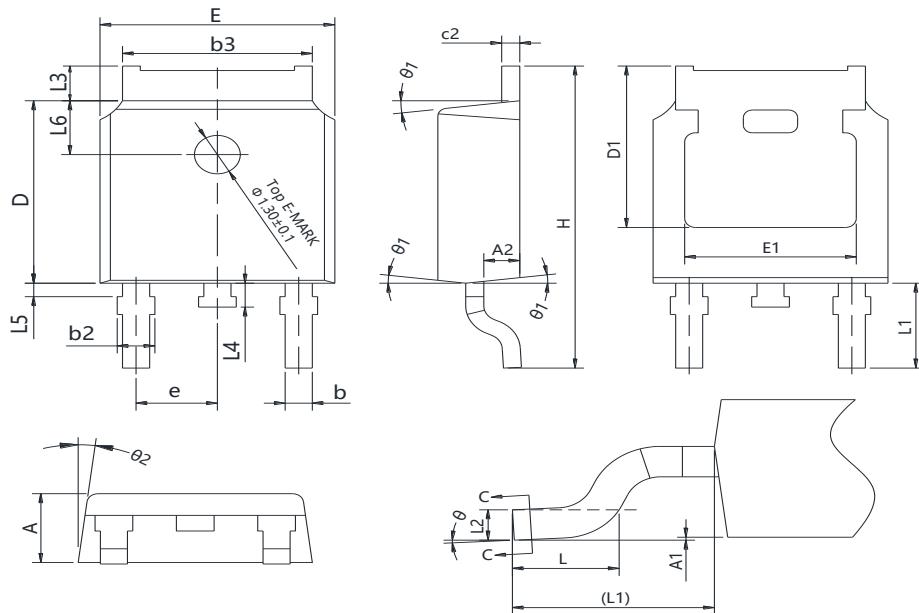
### Package Information



| Symbol | mm        |       |       |
|--------|-----------|-------|-------|
|        | Min       | Nom   | Max   |
| A      | 2.20      | 2.30  | 2.38  |
| A1     | 0.00      | -     | 0.20  |
| A2     | 0.97      | 1.07  | 1.17  |
| b      | 0.68      | 0.78  | 0.90  |
| b3     | 5.20      | 5.33  | 5.46  |
| c      | 0.43      | 0.53  | 0.61  |
| D      | 5.98      | 6.10  | 6.22  |
| D1     | 5.30 REF  |       |       |
| E      | 6.40      | 6.60  | 6.73  |
| E1     | 4.63      | -     | -     |
| e      | 2.286 BSC |       |       |
| H      | 9.40      | 10.10 | 10.50 |
| L      | 1.38      | 1.50  | 1.75  |
| L1     | 2.90 REF  |       |       |
| L2     | 0.51 BSC  |       |       |
| L3     | 0.88      | -     | 1.28  |
| L4     | 0.50      | -     | 1.00  |
| θ      | 0°        | -     | 8°    |

Version 1: TO252-P package outline dimension

## Package Information



| Symbol | mm        |       |       |
|--------|-----------|-------|-------|
|        | Min       | Nom   | Max   |
| A      | 2.20      | 2.30  | 2.38  |
| A1     | 0.00      | -     | 0.10  |
| A2     | 0.90      | 1.01  | 1.10  |
| b      | 0.72      | -     | 0.85  |
| b1     | 0.71      | 0.76  | 0.81  |
| b2     | 0.72      | -     | 0.90  |
| b3     | 5.13      | 5.33  | 5.46  |
| c      | 0.47      | -     | 0.60  |
| c1     | 0.46      | 0.51  | 0.56  |
| c2     | 0.47      | -     | 0.60  |
| D      | 6.00      | 6.10  | 6.20  |
| D1     | 5.25      | -     | -     |
| E      | 6.50      | 6.60  | 6.70  |
| E1     | 4.70      | -     | -     |
| e      | 2.186     | 2.286 | 2.386 |
| H      | 9.80      | 10.10 | 10.40 |
| L      | 1.40      | 1.50  | 1.70  |
| L1     | 2.90 REF  |       |       |
| L2     | 0.508 BSC |       |       |
| L3     | 0.90      | -     | 1.25  |
| L4     | 0.60      | 0.80  | 1.00  |
| L5     | 0.15      | -     | 0.75  |
| L6     | 1.80 REF  |       |       |
| θ      | 0°        | -     | 8°    |
| θ1     | 5°        | 7°    | 9°    |
| θ2     | 5°        | 7°    | 9°    |

Version 2: TO252-J package outline dimension

## Ordering Information

| Package Type | Units/Reel | Reels/Inner Box | Units/Inner Box | Inner Boxes/Carton Box | Units/Carton Box |
|--------------|------------|-----------------|-----------------|------------------------|------------------|
| TO252-P      | 2500       | 2               | 5000            | 5                      | 25000            |
| TO252-J      | 2500       | 2               | 5000            | 5                      | 25000            |

## Product Information

| Product     | Package | Pb Free | RoHS | Halogen Free |
|-------------|---------|---------|------|--------------|
| SFS04R02DNF | TO252   | yes     | yes  | yes          |

## Legal Disclaimer

The information given in this document shall in no event be regarded as a guarantee of conditions or characteristics. With respect to any examples or hints given herein, any typical values stated herein and/or any information regarding the application of the device, Oriental Semiconductor hereby disclaims any and all warranties and liabilities of any kind, including without limitation, warranties of non-infringement of intellectual property rights of any third party.

For further information on technology, delivery terms and conditions and prices, please contact the Oriental Semiconductor sales representatives ([www.orientalsemi.com](http://www.orientalsemi.com)).

© Oriental Semiconductor Co.,Ltd. All Rights Reserved